

ABSTRACT OF THE DISCLOSURE

In the present invention, a reference conductive layer
5 and a first surface conductive layer are respectively provided
on a surface and a back face of a first base film. The first
base film includes a first via hole penetrating the first
surface conductive layer. After a first electroless plating
layer and a first conductive material are sequentially grown on
10 a surface of the first base film, a first coating conductive
layer composed of the first electroless plating layer, the
first conductive material and the first surface conductive
layer, is etched to have a reduced thickness. Then, the first
coating conductive layer is patterned to form a first wiring
15 layer. In this manner, a desired pattern width can be obtained
even in the case where the first coating conductive layer is
patterned by isotropic etching such as wet etching.